

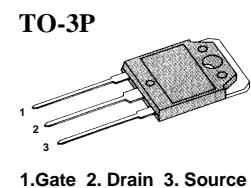
Advanced Power MOSFET

SSH45N20A

FEATURES

- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Lower Leakage Current : 10 μ A (Max.) @ $V_{DS} = 200V$
- Low $R_{DS(ON)}$: 0.054 Ω (Typ.)

$BV_{DSS} = 200\text{ V}$
 $R_{DS(on)} = 0.065\ \Omega$
 $I_D = 45\text{ A}$



Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
V_{DSS}	Drain-to-Source Voltage	200	V
I_D	Continuous Drain Current ($T_C=25^\circ\text{C}$)	45	A
	Continuous Drain Current ($T_C=100^\circ\text{C}$)	27.8	
I_{DM}	Drain Current-Pulsed ①	180	A
V_{GS}	Gate-to-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy ②	675	mJ
I_{AR}	Avalanche Current ①	45	A
E_{AR}	Repetitive Avalanche Energy ①	27.8	mJ
dv/dt	Peak Diode Recovery dv/dt ③	5.0	V/ns
P_D	Total Power Dissipation ($T_C=25^\circ\text{C}$)	278	W
	Linear Derating Factor	2.22	$W^\circ\text{C}$
T_J, T_{STG}	Operating Junction and Storage Temperature Range	- 55 to + 150	$^\circ\text{C}$
	Maximum Lead Temp. for Soldering Purposes, 1/8 " from case for 5-seconds	300	

Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
R_{JC}	Junction-to-Case	--	0.45	$^\circ\text{C}/\text{W}$
R_{CS}	Case-to-Sink	0.24	--	
R_{JA}	Junction-to-Ambient	--	40	

SAMSUNG

ELECTRONICS

SSH45N20A

N-CHANNEL
POWER MOSFET

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
BV_{DSS}	Drain-Source Breakdown Voltage	200	--	--	V	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$
$\Delta \text{BV}/\Delta T_J$	Breakdown Voltage Temp. Coeff.	--	0.20	--	$\text{V}/^\circ\text{C}$	$\text{I}_D=250\mu\text{A}$ See Fig 7
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	2.0	--	4.0	V	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=250\mu\text{A}$
I_{GSS}	Gate-Source Leakage , Forward	--	--	100	nA	$\text{V}_{\text{GS}}=30\text{V}$
	Gate-Source Leakage , Reverse	--	--	-100		$\text{V}_{\text{GS}}=-30\text{V}$
I_{DSS}	Drain-to-Source Leakage Current	--	--	10	μA	$\text{V}_{\text{DS}}=200\text{V}$
		--	--	100		$\text{V}_{\text{DS}}=160\text{V}, T_C=125^\circ\text{C}$
$\text{R}_{\text{DS(on)}}$	Static Drain-Source On-State Resistance	--	--	0.065	Ω	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=22.5\text{A}$ ④
g_{fs}	Forward Transconductance	--	25.06	--	S	$\text{V}_{\text{DS}}=40\text{V}, \text{I}_D=22.5\text{A}$ ④
C_{iss}	Input Capacitance	--	3030	3940	pF	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=25\text{V}, f=1\text{MHz}$ See Fig 5
C_{oss}	Output Capacitance	--	530	610		
C_{rss}	Reverse Transfer Capacitance	--	255	295		
$t_{\text{d(on)}}$	Turn-On Delay Time	--	22	60	ns	$\text{V}_{\text{DD}}=100\text{V}, \text{I}_D=45\text{A},$ $\text{R}_G=5.3\Omega$ See Fig 13 ④ ⑤
t_r	Rise Time	--	22	60		
$t_{\text{d(off)}}$	Turn-Off Delay Time	--	79	170		
t_f	Fall Time	--	36	80		
Q_g	Total Gate Charge	--	117	152	nC	$\text{V}_{\text{DS}}=160\text{V}, \text{V}_{\text{GS}}=10\text{V},$ $\text{I}_D=45\text{A}$ See Fig 6 & Fig 12 ④ ⑤
Q_{gs}	Gate-Source Charge	--	25	--		
Q_{gd}	Gate-Drain(" Miller ") Charge	--	48.8	--		

Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
I_s	Continuous Source Current	--	--	45	A	Integral reverse pn-diode in the MOSFET
I_{SM}	Pulsed-Source Current ①	--	--	180		
V_{SD}	Diode Forward Voltage ④	--	--	1.5	V	$T_J=25^\circ\text{C}, \text{I}_s=45\text{A}, \text{V}_{\text{GS}}=0\text{V}$
t_{rr}	Reverse Recovery Time	--	210	--	ns	$T_J=25^\circ\text{C}, I_F=45\text{A}$ $dI_F/dt=100\text{A}/\mu\text{s}$ ④
Q_{rr}	Reverse Recovery Charge	--	1.67	--		

Notes :

① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature

② $L=0.5\text{mH}, \text{I}_{\text{AS}}=45\text{A}, \text{V}_{\text{DD}}=50\text{V}, \text{R}_G=27\Omega$ Starting $T_J=25^\circ\text{C}$

③ $\text{I}_{\text{SD}} \leq 45\text{A}, dI/dt \leq 370\text{A}/\mu\text{s}, \text{V}_{\text{DD}} \leq \text{BV}_{\text{DSS}}$, Starting $T_J=25^\circ\text{C}$

④ Pulse Test : Pulse Width = $250\mu\text{s}$, Duty Cycle $\leq 2\%$

⑤ Essentially Independent of Operating Temperature

**N-CHANNEL
POWER MOSFET**

SSH45N20A

Fig 1. Output Characteristics

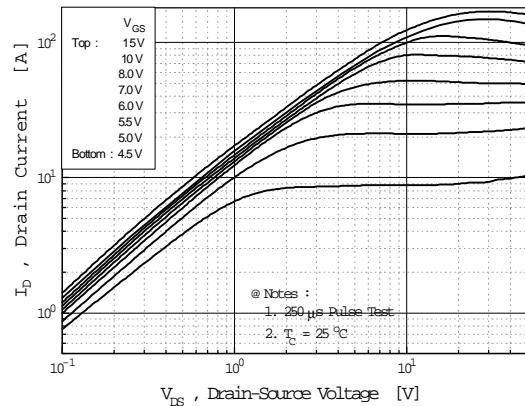


Fig 2. Transfer Characteristics

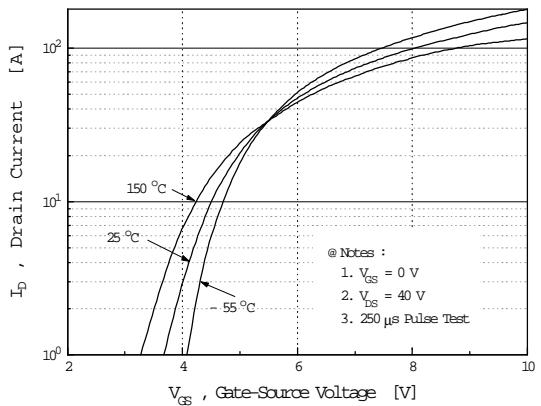


Fig 3. On-Resistance vs. Drain Current

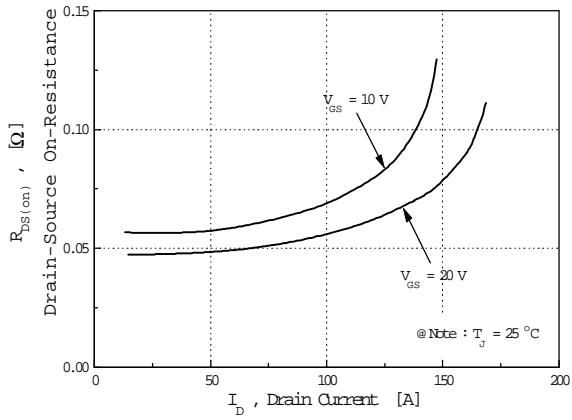


Fig 4. Source-Drain Diode Forward Voltage

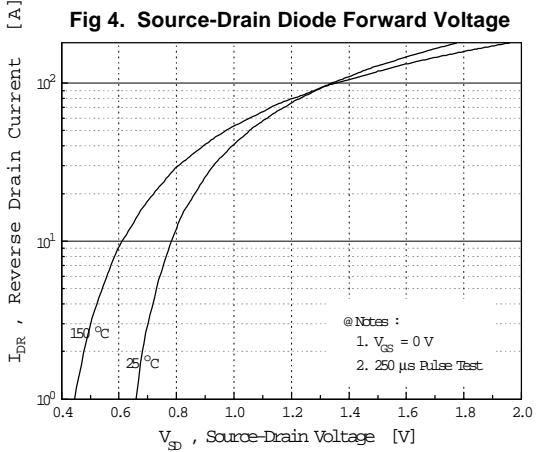


Fig 5. Capacitance vs. Drain-Source Voltage

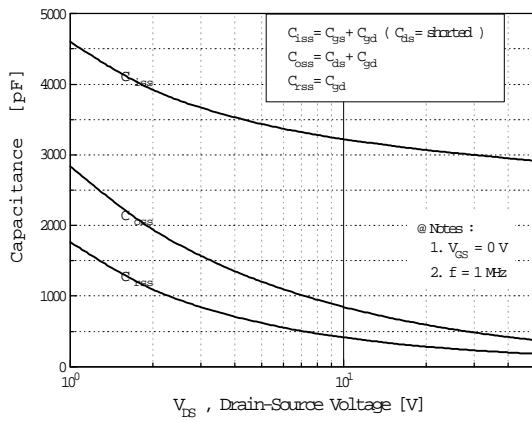
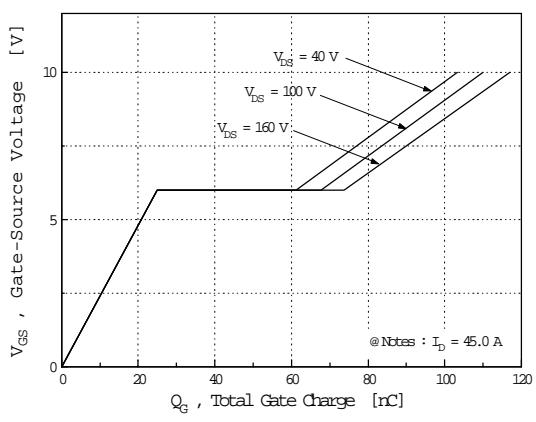
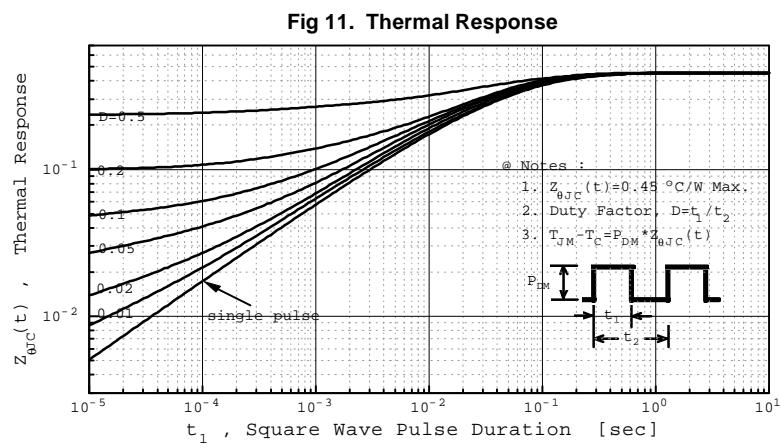
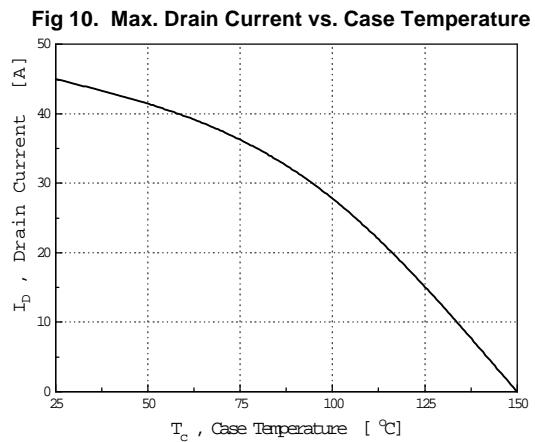
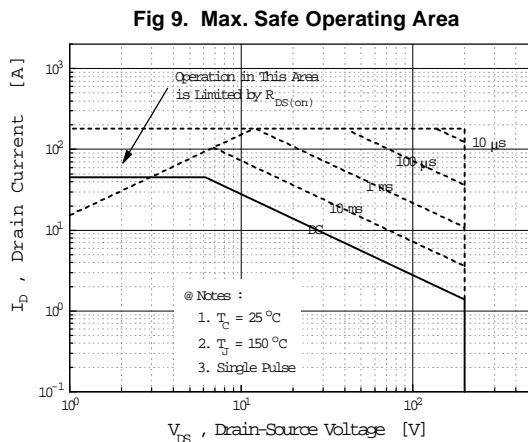
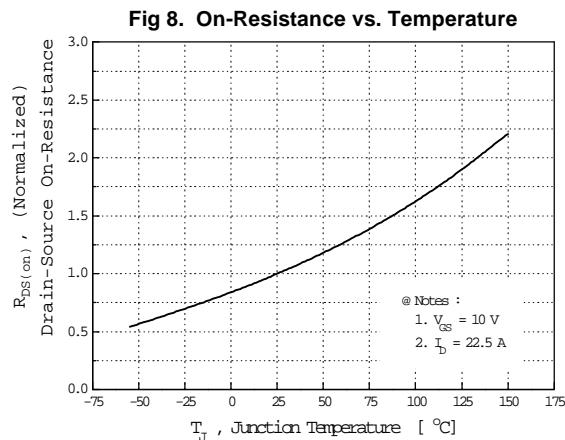
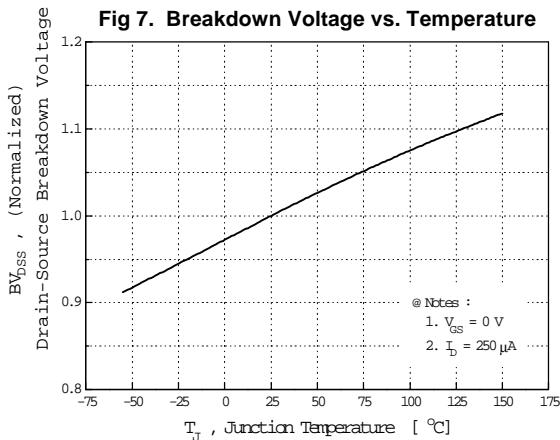


Fig 6. Gate Charge vs. Gate-Source Voltage



SSH45N20A

N-CHANNEL
POWER MOSFET



**N-CHANNEL
POWER MOSFET**

SSH45N20A

Fig 12. Gate Charge Test Circuit & Waveform

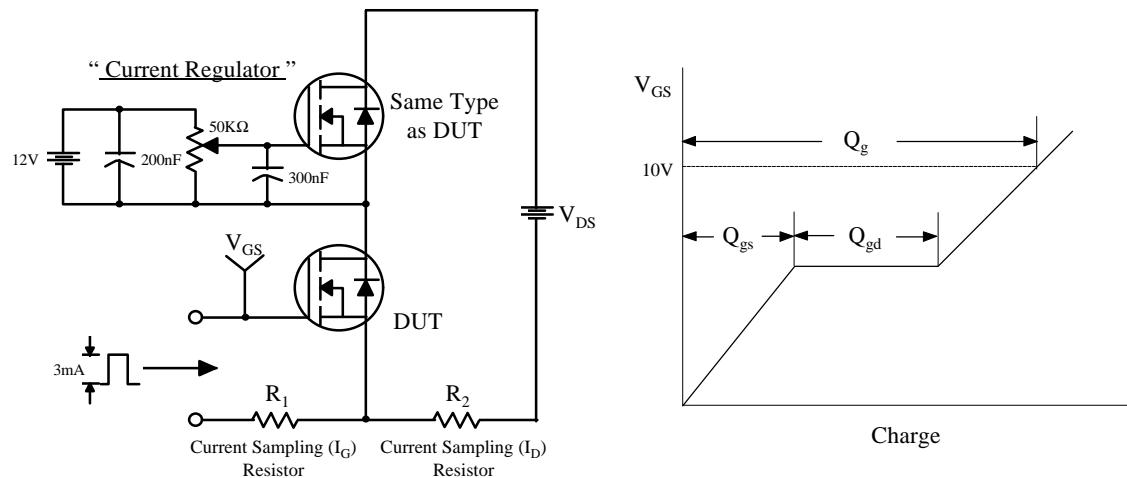


Fig 13. Resistive Switching Test Circuit & Waveforms

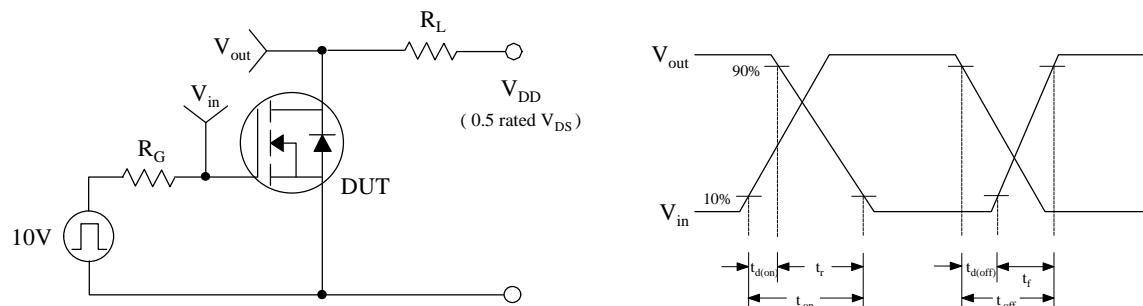
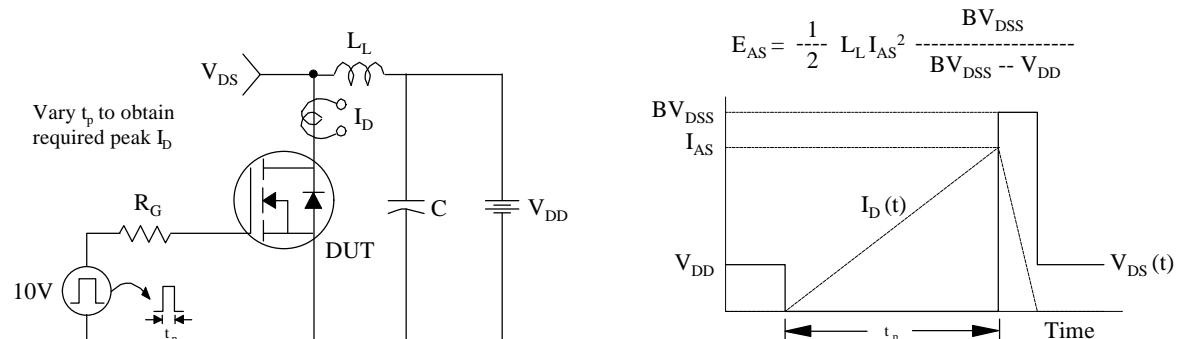


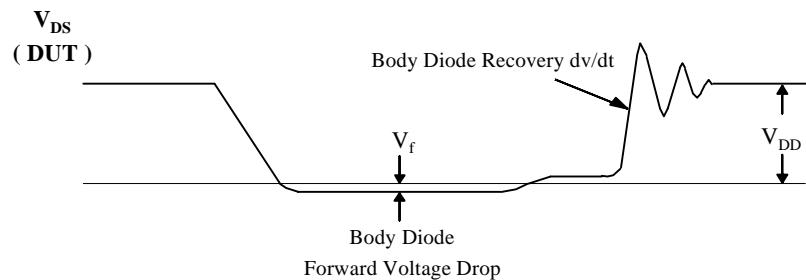
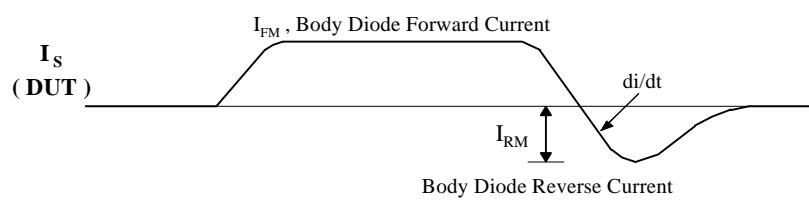
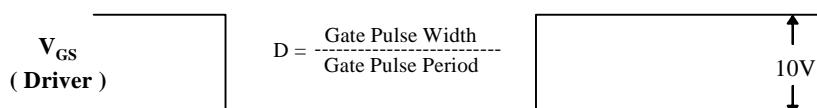
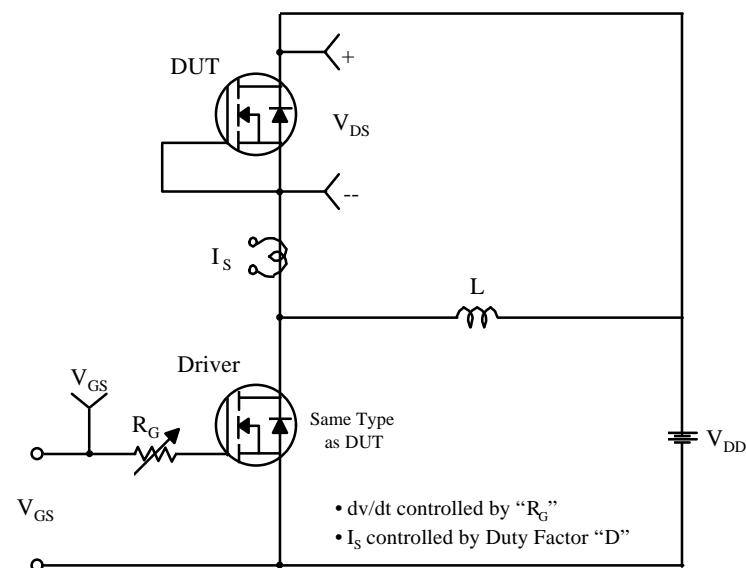
Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms



SSH45N20A

N-CHANNEL
POWER MOSFET

Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



SAMSUNG

ELECTRONICS